

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Hyper Red	645	-	nm
Dominant Wavelength I _F = 20mA	$\lambda_{\text{dom}}^{[1]}$	Hyper Red	630	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	$\Delta\lambda$	Hyper Red	28	-	nm
Capacitance	C	Hyper Red	35	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Hyper Red	1.95	2.5	V
Reverse Current (V _R = 5V)	I _R	Hyper Red	-	10	μA

Notes:1. The dominant wavelength (λ_d) above is the setup value of the sorting machine. (Tolerance λ_d : $\pm 1\text{nm}$.)2. Forward voltage: $\pm 0.1\text{V}$.

3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	75	mW
Reverse Voltage	V _R	5	V
Junction Temperature	T _j	115	°C
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T _{stg}	-40 to +85	°C
DC Forward Current	I _F	30	mA
Peak Forward Current	I _{FM} ^[1]	185	mA
Electrostatic Discharge Threshold (HBM)	-	3000	V

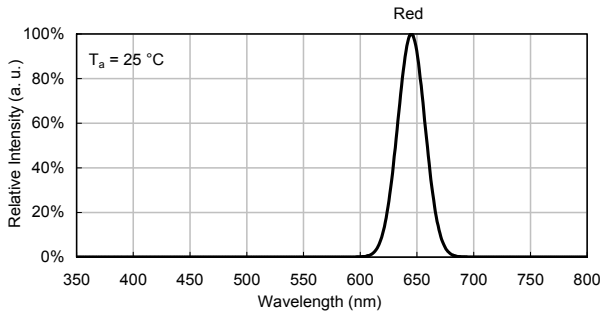
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

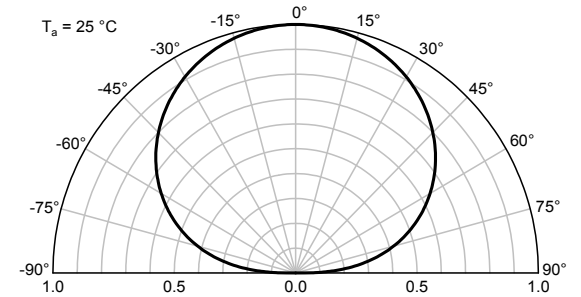
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH

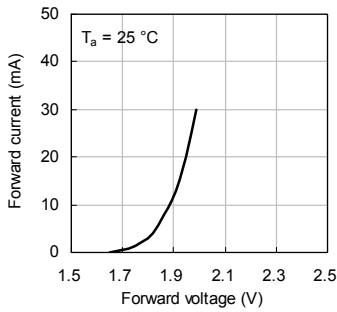


SPATIAL DISTRIBUTION

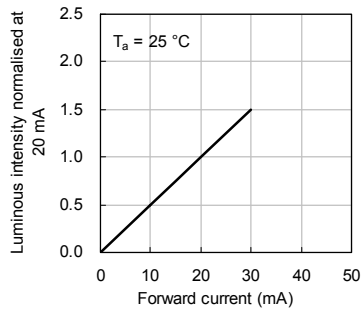


HYPER RED

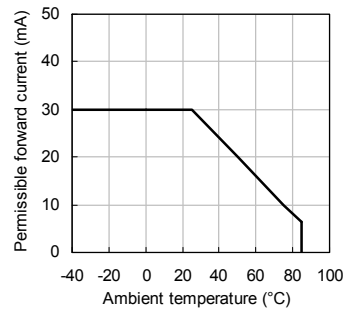
Forward Current vs. Forward Voltage



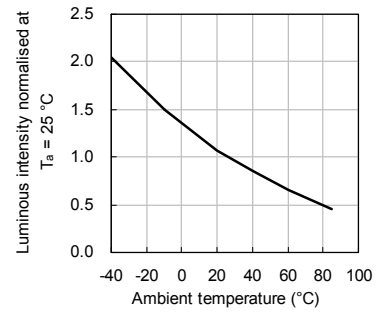
Luminous Intensity vs. Forward Current



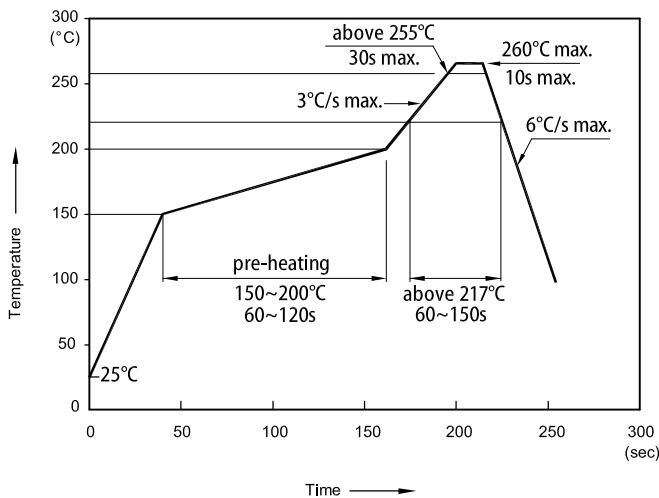
Forward Current Derating Curve



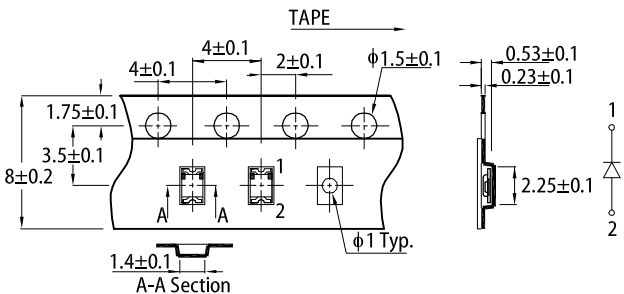
Luminous Intensity vs. Ambient Temperature



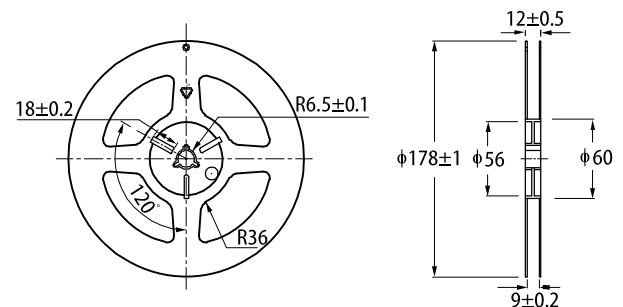
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



TAPE SPECIFICATIONS (units : mm)

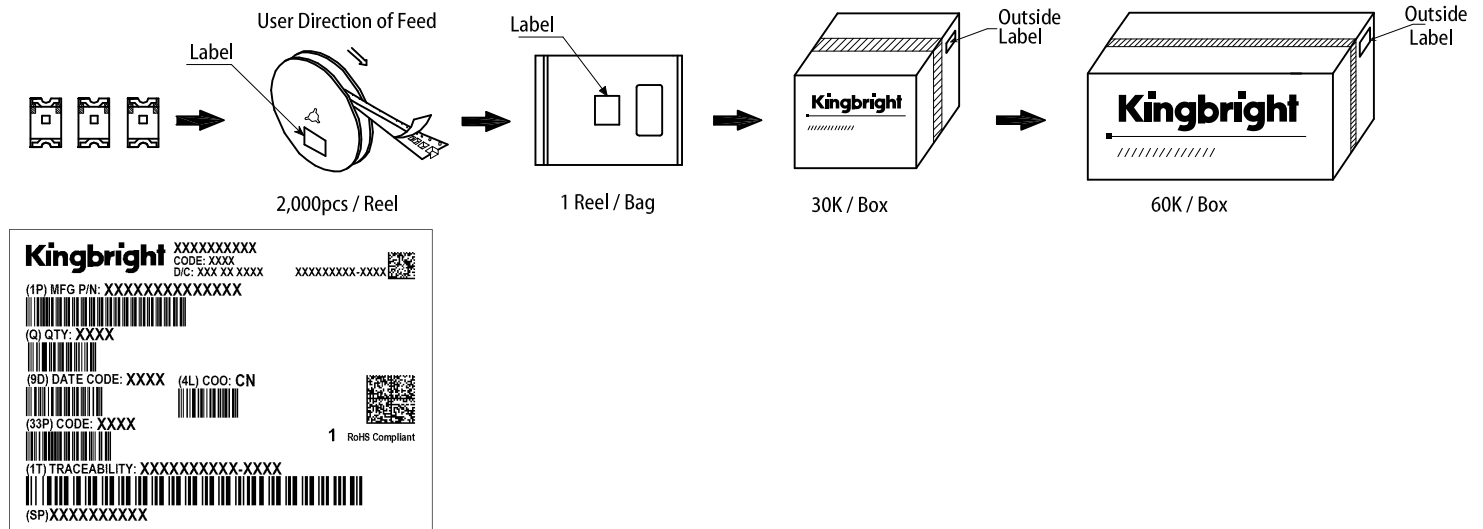


REEL DIMENSION (units : mm)



- Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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